IN THE SPECIFICATION

Page 2, line 1, please delete "BACKGROUND OF THE INVENTION" and insert therein:

PROCESSING SYSTEM INCLUDING PROCESSING TOOL AND SILICON WORK-PIECE IN COMBINATION AND METHOD FOR CARRYING OUT FIXED-ABRASIVE GRINDING PROCESS ON SILICON WORK-PIECE

CROSS-REFERENCE TO RELATED APPLICATIONS

Page 2, between lines 8 and 9, please insert, as follows:

BACKGROUND OF THE INVENTION

Page 2, line 9, please change " 1. Field of the Invention" to:

1. Field of the Invention

Page 2, line 18, please change " 2. Description of the Related Art" to:

2. Discussion of the Background

Please replace the paragraph beginning at page 2, line 2, with the following rewritten paragraph:

This application is a divisional application of, and claims the priority to, Serial Number 09/639,239, filed August 16, 2000 and claims the benefit of Japanese Patent Applications No. 11-237467 filed August 24, 1999, No. 11-260799 filed September 14, 1999, No. 11-278608 filed September 30, 1999 and No. 11-206355 filed October 28, 1999, in the Japanese Patent Office, the disclosures of which are herby incorporated by reference.